

### General Description

The AO4484 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  with low gate charge. This is an all purpose device that is suitable for use in a wide range of power conversion applications.

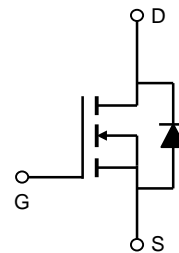
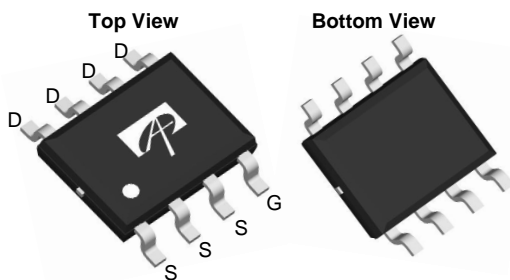
### Product Summary

$V_{DS}$  (V) = 40V  
 $I_D$  = 10A ( $V_{GS}$  = 10V)  
 $R_{DS(ON)}$  < 10m $\Omega$  ( $V_{GS}$  = 10V)  
 $R_{DS(ON)}$  < 12m $\Omega$  ( $V_{GS}$  = 4.5V)

100% UIS Tested  
 100% Rg Tested



### SOIC-8



### Absolute Maximum Ratings $T_J=25^\circ\text{C}$ unless otherwise noted

| Parameter   | Symbol         | 10 Sec                 | Steady State | Units            |   |
|---|----------------|------------------------|--------------|------------------|---|
| Drain-Source Voltage                                      | $V_{DS}$       | 40                     |              | V                |   |
| Gate-Source Voltage                                       | $V_{GS}$       | $\pm 20$               |              | V                |   |
| Continuous Drain Current <sup>A</sup>                     | $I_D$          | $T_A=25^\circ\text{C}$ | 13.5         | 10               | A |
|   |                | $T_A=70^\circ\text{C}$ | 10.8         | 8                |   |
| Pulsed Drain Current <sup>B</sup>                         | $I_{DM}$       | 120                    |              |                  |   |
| Avalanche Current <sup>G</sup>                            | $I_{AR}$       | 23                     |              |                  |   |
| Repetitive avalanche energy $L=0.3\text{mH}$ <sup>G</sup> | $E_{AR}$       | 79                     |              | mJ               |   |
| Power Dissipation <sup>A</sup>                            | $P_D$          | $T_A=25^\circ\text{C}$ | 3.1          | 1.7              | W |
|   |                | $T_A=70^\circ\text{C}$ | 2.0          | 1.1              |   |
| Junction and Storage Temperature Range                    | $T_J, T_{STG}$ | -55 to 150             |              | $^\circ\text{C}$ |   |

### Thermal Characteristics

| Parameter                                | Symbol          | Typ          | Max | Units              |
|--|-----------------|--------------|-----|--------------------|
| Maximum Junction-to-Ambient <sup>A</sup> | $R_{\theta JA}$ | 31           | 40  | $^\circ\text{C/W}$ |
| Maximum Junction-to-Ambient <sup>A</sup> |                 | Steady State | 59  | 75                 |
| Maximum Junction-to-Lead <sup>C</sup>    | $R_{\theta JL}$ | 16           | 24  | $^\circ\text{C/W}$ |

Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

| Symbol                      | Parameter                             | Conditions  | Min | Typ         | Max      | Units |
|-----------------------------|---------------------------------------|---|-----|-------------|----------|-------|
| <b>STATIC PARAMETERS</b>    |                                       |   |     |             |          |       |
| B <sub>V</sub> DSS          | Drain-Source Breakdown Voltage        | I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V  | 40  |             |          | V     |
| I <sub>D</sub> DSS          | Zero Gate Voltage Drain Current       | V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V<br>T <sub>J</sub> = 55°C                        |     |             | 1<br>5   | μA    |
| I <sub>GSS</sub>            | Gate-Body leakage current             | V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V  |     |             | ±100     | nA    |
| V <sub>GS(th)</sub>         | Gate Threshold Voltage                | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA                                  | 1.7 | 2.2         | 3        | V     |
| I <sub>D(ON)</sub>          | On state drain current                | V <sub>GS</sub> = 10V, V <sub>DS</sub> = 5V   | 120 |             |          | A     |
| R <sub>DS(ON)</sub>         | Static Drain-Source On-Resistance     | V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A<br>T <sub>J</sub> = 125°C                       |     | 8.2<br>12.5 | 10<br>16 | mΩ    |
|                             |                                       | V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 8A   |     | 10          | 12.5     |       |
| g <sub>FS</sub>             | Forward Transconductance              | V <sub>DS</sub> = 5V, I <sub>D</sub> = 10A  |     | 75          |          | S     |
| V <sub>SD</sub>             | Diode Forward Voltage                 | I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V   |     | 0.72        | 1        | V     |
| I <sub>S</sub>              | Maximum Body-Diode Continuous Current |   |     |             | 2.5      | A     |
| <b>DYNAMIC PARAMETERS</b>   |                                       |   |     |             |          |       |
| C <sub>iss</sub>            | Input Capacitance                     | V <sub>GS</sub> = 0V, V <sub>DS</sub> = 20V, f = 1MHz                                       |     | 1500        | 1950     | pF    |
| C <sub>oss</sub>            | Output Capacitance                    |   |     | 215         |          | pF    |
| C <sub>rss</sub>            | Reverse Transfer Capacitance          |   |     | 135         |          | pF    |
| R <sub>g</sub>              | Gate resistance                       | V <sub>GS</sub> = 0V, V <sub>DS</sub> = 0V, f = 1MHz  | 2   | 3.5         | 5        | Ω     |
| <b>SWITCHING PARAMETERS</b> |                                       |   |     |             |          |       |
| Q <sub>g</sub> (10V)        | Total Gate Charge                     | V <sub>GS</sub> = 10V, V <sub>DS</sub> = 20V, I <sub>D</sub> = 10A                          |     | 27.2        | 37       | nC    |
| Q <sub>g</sub> (4.5V)       | Total Gate Charge                     |   |     | 13.6        | 18       | nC    |
| Q <sub>gs</sub>             | Gate Source Charge                    |   |     | 4.5         |          | nC    |
| Q <sub>gd</sub>             | Gate Drain Charge                     |   |     | 6.4         |          | nC    |
| t <sub>D(on)</sub>          | Turn-On Delay Time                    | V <sub>GS</sub> = 10V, V <sub>DS</sub> = 20V, R <sub>L</sub> = 2Ω,<br>R <sub>GEN</sub> = 3Ω |     | 6.4         |          | ns    |
| t <sub>r</sub>              | Turn-On Rise Time                     |   |     | 17.2        |          | ns    |
| t <sub>D(off)</sub>         | Turn-Off Delay Time                   |   |     | 29.6        |          | ns    |
| t <sub>f</sub>              | Turn-Off Fall Time                    |   |     | 16.8        |          | ns    |
| t <sub>rr</sub>             | Body Diode Reverse Recovery Time      | I <sub>F</sub> = 10A, dI/dt = 100A/μs   |     | 30          | 40       | ns    |
| Q <sub>rr</sub>             | Body Diode Reverse Recovery Charge    | I <sub>F</sub> = 10A, dI/dt = 100A/μs   |     | 19          |          | nC    |

A: The value of R<sub>θJA</sub> is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub> = 25°C. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C: The R<sub>θJA</sub> is the sum of the thermal impedance from junction to lead R<sub>θJL</sub> and lead to ambient.

D: The static characteristics in Figures 1 to 6 are obtained using t ≤ 300μs pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub> = 25°C. The SOA curve provides a single pulse rating.

F: The current rating is based on the t ≤ 10s thermal resistance rating.

G: E<sub>AR</sub> and I<sub>AR</sub> ratings are based on low frequency and duty cycles to keep T<sub>J</sub> = 25°C.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

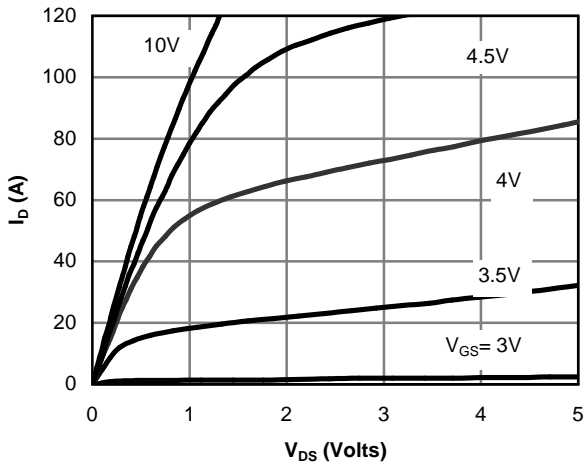


Figure 1: On-Region Characteristics

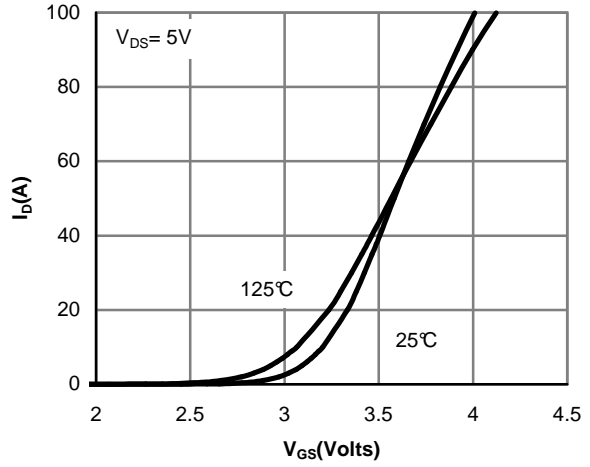


Figure 2: Transfer Characteristics

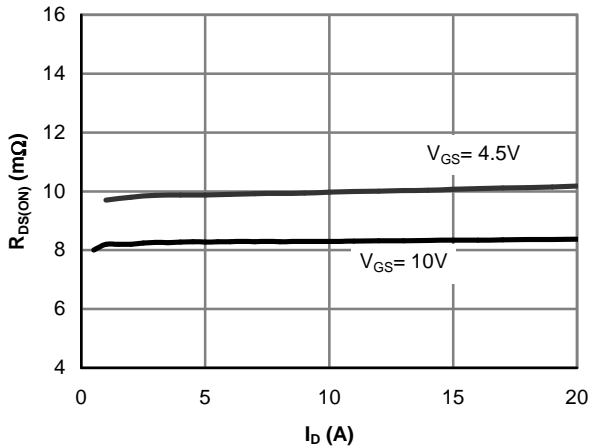


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

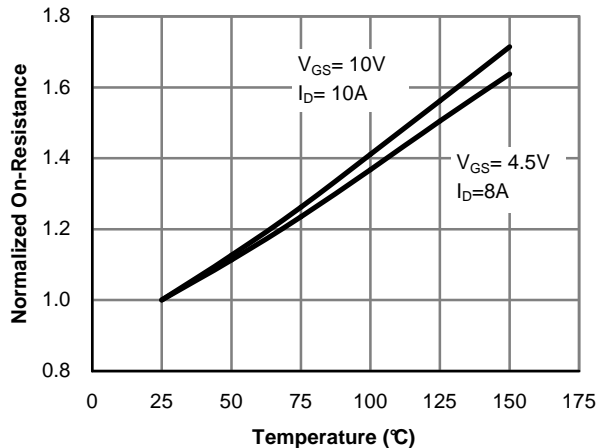


Figure 4: On-Resistance vs. Junction Temperature

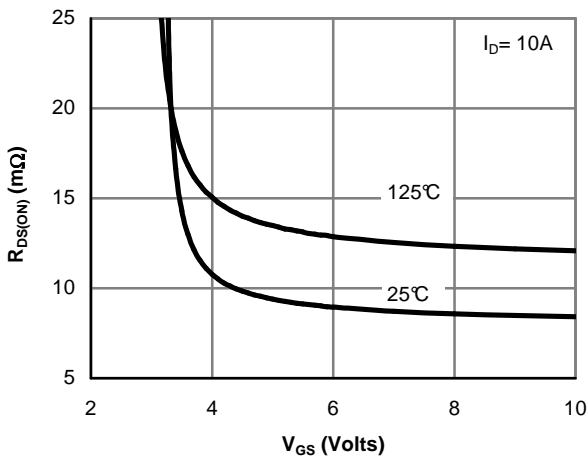


Figure 5: On-Resistance vs. Gate-Source Voltage

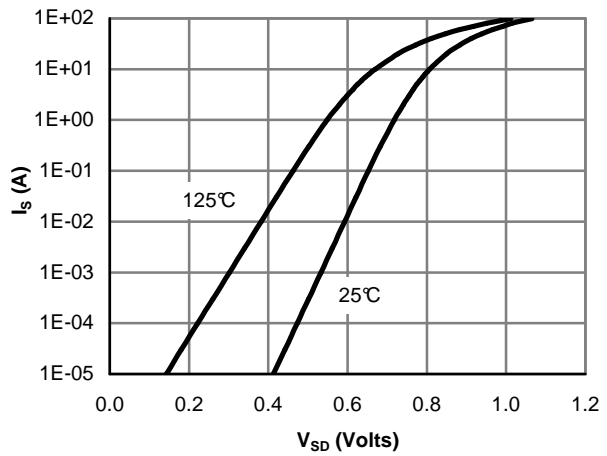


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

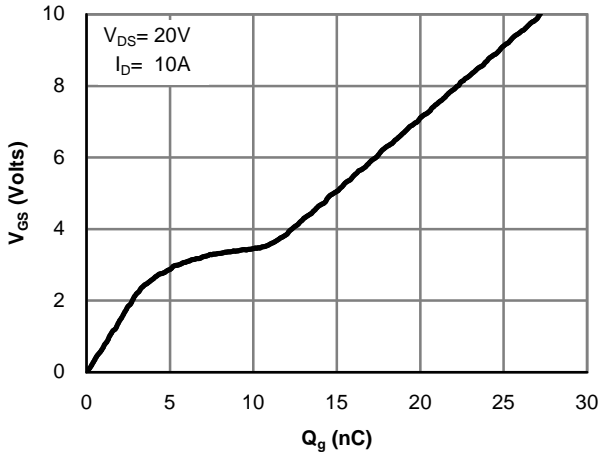


Figure 7: Gate-Charge Characteristics

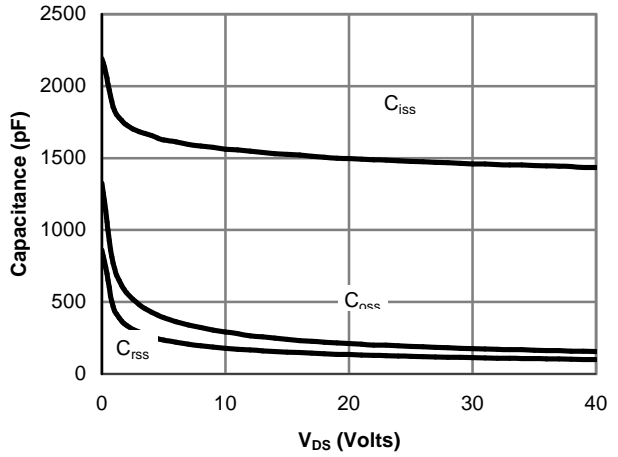


Figure 8: Capacitance Characteristics

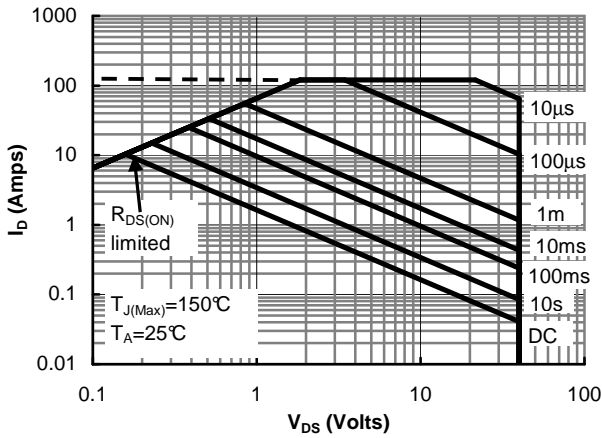


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

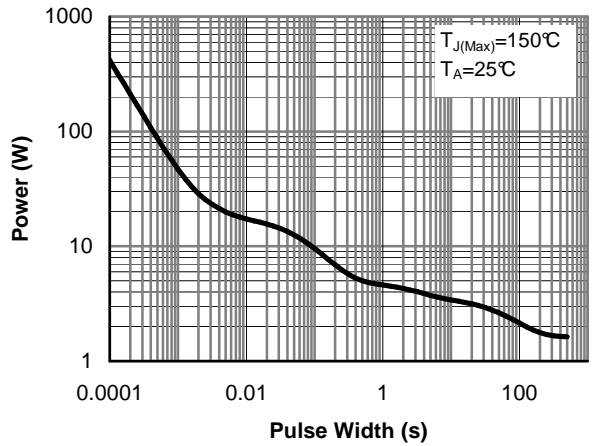


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

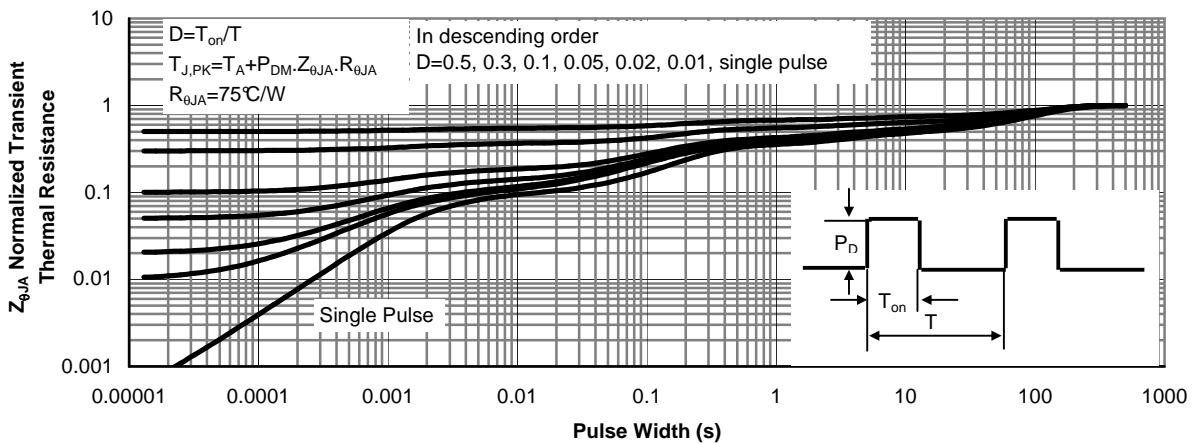


Figure 11: Normalized Maximum Transient Thermal Impedance (Note E)

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